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ABSTRACT

A molded plastic package incorporates a lead frame which includes a plurality of leads radially aligned around a central opening. A die is mounted in the central opening and is electrically connected to the leads by wire bonding. A molded plastic casing is formed over the die, wiring and lead frame to encapsulate the package. The lower surfaces of the die and lead frame are exposed through the package. A method for making the molded plastic package includes mounting the die and lead frame onto an adhesive tape, electrically connecting the die to the leads by wire bonding, forming a molded plastic casing over the die, wire bonding and lead frame, and then removing the adhesive tape to expose the lower surfaces of the die and the lead frame.